· · · · · · · · · · · · · · · · · · ·	Application No.	Applicant(s)
Notice of Allowability	09/881,407	WANG, ZHONGZE
	Examiner	Art Unit
	Pamela E. Perkins	2822
The MAILING DATE of this communication appeal claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIOF the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this appropriate communication IGHTS. This application is subject	oplication. If not included in will be mailed in due course. THIS
1. 🛮 This communication is responsive to the after-fianl amendi	ment filed on 19 May 2005.	
2. ☑ The allowed claim(s) is/are <u>1-5 and 26-35</u> .		
3. \boxtimes The drawings filed on <u>13 June 2001</u> are accepted by the E	xaminer.	
 4. ☐ Acknowledgment is made of a claim for foreign priority ur a) ☐ All b) ☐ Some* c) ☐ None of the: 1. ☐ Certified copies of the priority documents have 2. ☐ Certified copies of the priority documents have 3. ☐ Copies of the certified copies of the priority documents have International Bureau (PCT Rule 17.2(a)). * Certified copies not received: 	e been received. e been received in Application No	** *
Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONN THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 5. A SUBSTITUTE OATH OR DECLARATION must be subm INFORMAL PATENT APPLICATION (PTO-152) which give	IENT of this application. itted. Note the attached EXAMINER	R'S AMENDMENT or NOTICE OF
<u> </u>	•	ation is delicient.
6. CORRECTED DRAWINGS (as "replacement sheets") mus		0.040) -#
 (a) ☐ including changes required by the Notice of Draftspers 1) ☐ hereto or 2) ☐ to Paper No./Mail Date 		-946) attached
	•	Office and in the second
(b) ☐ including changes required by the attached Examiner's Paper No./Mail Date	s Amendment / Comment of in the t	Office action of
· Identifying indicia such as the application number (see 37 CFR 1 each sheet. Replacement sheet(s) should be labeled as such in t	.84(c)) should be written on the drawi he header according to 37 CFR 1.121	ngs in the front (not the back) of (d).
 DEPOSIT OF and/or INFORMATION about the depo- attached Examiner's comment regarding REQUIREMENT 	sit of BIOLOGICAL MATERIAL FOR THE DEPOSIT OF BIOLOGIC	must be submitted. Note the CAL MATERIAL.
Attachment(s)		the state of the s
1. Notice of References Cited (PTO-892)	5. Notice of Informal F	Patent Application (PTO-152)
2. Notice of Draftperson's Patent Drawing Review (PTO-948)	6. Interview Summary	
 Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date 	Paper No./Mail Da 08), 7. 🗍 Examiner's Amend	
4. Examiner's Comment Regarding Requirement for Deposit	8. 🛛 Examiner's Statem	ent of Reasons for Allowance
of Biological Material	9. Other	AMIR ZARABIAN SMECON BOTEST EVANGMED
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DETAILED ACTION

This office action is in response to the filing of the after-final amendment on 19 May 2005. Claims 1-5 and 26-35 are pending; claims 61-67 have been cancelled.

Allowable Subject Matter

Claims 1-5 and 26-35 are allowed.

Reasons for Allowance

The following is an examiner's statement of reasons for allowance: prior art does not anticipate, teach, or suggest a method of forming a transistor device where a silicon-comprising surface is exposed to activated nitrogen to increase a peak nitrogen concentration within the silicon-comprising surface by at least 15% (atom percent), the exposing forming a material comprising silicon and nitrogen; providing a channel region on one side of the material, comprising silicon and nitrogen; providing a transistor gate structure on a side of the material comprising silicon and nitrogen that is opposed to the one side; and forming a pair of source/drain regions separated from one another by the channel region.

For example, Chau (5,763,922) discloses a method of forming a transistor device where a silicon-comprising surface of silicon dioxide is exposed to activate nitrogen to convert the silicon-comprising surface to a material comprising silicon and nitrogen; the activated nitrogen being formed by exposing a nitrogen-containing precursor to a plasma maintained at a power of 500 watts to 2,000 watts; providing a channel region

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on one side of the silicon and nitrogen surface; forming a plurality of PMOS or NMOS transistor gate structures on a side of the silicon and nitrogen surface opposed to the one side and forming a pair of source and drain regions separated from one another by the channel region.

Chau further discloses dividing the transistor gate structures into a first group and a second group and forming a mask over the second group during the exposure step. Chau also discloses the plasma as a remote relative to the silicon-comprising surface and the plasma contacting the silicon-comprising surface. Chau discloses implanting a dopant into the channel region with a concentration between 1x10¹⁶ atoms/cm³ to 1x10¹⁷ atoms/cm³. However, Chau does not disclose, anticipate, teach, or suggest exposing the substrate surface to activated nitrogen to increase a peak nitrogen concentration within the substrate surface by at least about 15 atom percent.

Buchannan et al. (6,566,281) disclose a method of forming a transistor device where a silicon-comprising surface is exposed to activate nitrogen to convert the silicon-comprising surface to a material comprising silicon and nitrogen (col. 7, lines 48-67).

Buchannan et al. further disclose the activated nitrogen having a concentration of about 15 atomic % (col. 8, lines 1-10). However, Buchannan et al. do not disclose, aniticipate, teach or suggest exposing the substrate surface to activated nitrogen to increase a peak nitrogen concentration within the substrate surface by at least about 15 atom percent.

Yasuda et al. (6,756,635) disclose a method of forming a transistor device where a silicon-comprising surface of silicon dioxide (6) is exposed to activate nitrogen to

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convert the silicon-comprising surface (6) to a material comprising silicon and nitrogen (11) (col. 7, lines 43-48), wherein the surface has a thickness of 1nm¹ (abstract). Yasuda et al. further disclose the activated nitrogen having a concentration of about 15 atomic % (col. 7, lines 43-51; col. 11, line 60 thru col. 12, line 8). However, Yasuda et al. do not qualify as prior art.

The prior art made of record in this action does not anticipate, teach, or suggest a method of forming a transistor device where a silicon-comprising surface is exposed to activated nitrogen to increase a peak nitrogen concentration within the silicon-comprising surface by at least 15% (atom percent), the exposing forming a material comprising silicon and nitrogen; providing a channel region on one side of the material comprising silicon and nitrogen; providing a transistor gate structure on a side of the material comprising silicon and nitrogen that is opposed to the one side; and forming a pair of source/drain regions separated from one another by the channel region.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion -

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Pamela E. Perkins whose telephone number is (571)

 $^{^{1}}$ 1 nm = 10 Å

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272-1840. The examiner can normally be reached on Monday thru Friday, 9:00am to 5:30pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on (571) 272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

PEP

AMER ZARABIAN

THE SORY PATENT EXAMINER